PCN Number:	20180110005	PCN D	ate:	February 12, 2018	
Title: Datasheet fo	r LM5141-Q1				
Customer Contact:	PCN Manager			Dept: Quality Services	
Change Type:					
Assembly Site		Design		Wafer Bump Site	
Assembly Process		Data Sheet		Wafer Bump Material	
Assembly Material	s 🗌	Part number chan	ge	Wafer Bump Process	
Mechanical Specification		Test Site		Wafer Fab Site	
Packing/Shipping/	Labeling	Test Process		Wafer Fab Materials	
				Wafer Fab Process	
Notification Details					
Description of Change:					
Texas Instruments Incorporated is announcing an information only notification.					
The product datasheet(s) is being updated as summarized below.					
The following change history provides further details.					
-					
TEXAS INSTRUMENTS				LM5141-Q1	
INSTRUMENTS			SI	VSAJ6D -JULY 2016-REVISED DECEMBER 2017	
Changes from Revision C (February 2017) to Revision D Page					
Added top navigator icon for TI Design reference design					
Changed "CDS18534Q5A" to "CSD18534Q5A" to fix typo					
Changed "+" to "×" in Equation 56					
The datasheet number	will be changing				
Device Family		Change From:		Change To:	
LM5141-Q1		SNVSAJ6C		SNVSAJ6D	
These changes may be reviewed at the datasheet links provided.					
http://www.ti.com/pro	<u>auct/LM5141-Q1</u>				
Reason for Change:					
To accurately reflect de	evice characterist	ics.			
			r Relia	bility (positive / negative):	
				ent only. There are no changes	
to the actual device.		Jere Jere Jere J		,	
Changes to product identification resulting from this PCN:					
None.					
Product Affected:					
LM5141QRGERQ1	LM5141QRGET	01			
		τ-			
			o the re	gional contacts shown below	
or your local Field Sales Representative.					

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com